

AMENDMENTS TO THE SPECIFICATION

Please replace the Abstract of the disclosure section, located immediately following the Claims, with the following replacement Abstract:

An object is to provide a molded product, which has dielectric properties that the conventional liquid crystal polyester resin has not realized, and simultaneously which keeps a heat resistance such as solder reflow of a liquid crystal polyester, and which is used in information and telecommunications equipment employed in high frequency band regions such as microwaves and millimeter waves. A molded product of a wholly aromatic liquid crystal polyester resin composition which has having a dielectric constant of 3.0 or less and a dielectric dissipation factor of 0.04 or less and which is obtained by an injection molding of a composition comprising 90 to 45 percent by weight of the wholly aromatic liquid crystal polyester having a melting point of 320C or more, 10 to 40 percent by weight of an inorganic spherical hollow material having an aspect ratio of 2 or less, and 0 to 15 percent by weight (100 percent by weight in total) of an inorganic filler

having an aspect ratio of 4 or more. The molded product of the present invention has dielectric properties suitable for information and telecommunications equipment, and is excellent in solder heat resistance, processability, and dimensional stability. so that the molded product is advantageous as a substrate material for use in information and telecommunications equipment such as a cellular mobile phone and as a fixing/holding or a holding member of a transmitter-receiver element.

Please replace Table 2 at page 20, line 1 with the following replacement Table 2, marked-up to show changes relative to the original:

Table 2

	Specific Gravity of Resin Composition	Fracture Rate <u>X</u>	Fractured Micro Hollow Body (E) (wt%)	(D+E) /C	Relative Di-electric Constant	Dielectric Dissipation Factor	Soldering Heat Resistance (°C)	Surface Property of Product	Flowability Evaluation
Example 1	1.11	<u>0.048</u>	<u>0.81.0</u>	<u>0.040.05</u>	2.73	0.026	330	o	o
Example 2	1.01	<u>0.045</u>	<u>1.51.4</u>	0.05	2.64	0.023	325	o	o
Example 3	1.20	<u>0.085</u>	<u>1.41.3</u>	<u>0.430.42</u>	2.91	0.030	330	o	o
Example 4	1.04	<u>0.094</u>	<u>3.23.0</u>	<u>0.380.34</u>	2.85	0.026	330	o	o
Example 5	1.04	<u>0.088</u>	<u>2.92.8</u>	<u>0.370.34</u>	2.86	0.027	320	o	o
Example 6	1.07	<u>0.090</u>	3.6	<u>0.100.09</u>	2.84	0.023	320	o	o
Comparative Example 1	1.06	<u>0.0456</u>	<u>27.027.4</u>	<u>0.820.46</u>	3.11	0.022	330	x	x
Comparative Example 2	1.38	—	—	—	3.02	0.035	300	x	o
Comparative Example 3	1.24	<u>0.0460</u>	<u>40.510.8</u>	<u>0.540.36</u>	3.12	0.031	330	o	o
Comparative Example 4	1.02	<u>0.071</u>	<u>2.42.1</u>	<u>0.090.07</u>	2.68	0.025	300 or less	o	o
Comparative Example 5	1.60	—	—	—	3.61	0.033	340	o	o
Comparative Example 6	1.62	—	—	—	3.65	0.034	330	o	o